

**ABSTRACT OF THE DISCLOSURE**

A modular inductor arrangement is provided in which a footprint of an enclosure for single or multiple phase inductors provides enhanced thermal transfer. The inductor coil may be wound about an axis generally parallel to a mounting surface of the package, so as to provide for reduced height and expanded footprint dimensions. The inductor package may be mounted on a thermal support, such as a fluid-cooled support. Heat is extracted from the assembly during operation, so as to establish a reduced maximum internal temperature as compared to here for known structures. The arrangement may be included in various circuit configurations, such as power converters. Other components may be incorporated and integrated into the package, including sensors, capacitor coils, other inductor coils, and so forth.